



ABV-Indian Institute of Information Technology & Management, Gwalior

(Institute of National Importance under MoE, GOI)

Semester Internship (Aug. – Dec. 2026)

IEEE EPS - Undergraduate Hands-on-Experience (IEEE EPS-UHE)

Application Link:

<https://forms.gle/Y2BFsLx9iQv6hkaW9>



About IEEE EPS-UHP:

IEEE Electronics Packaging (EPS) Society is initiating a program to introduce undergraduate students to the research that is currently occurring at their universities. The program objective is to facilitate internship-like experience in microelectronics research to sophomore students at accredited universities. The program is available to US universities or colleges that have microelectronics packaging related research in areas such as: material characterization, reliability assessment, mechanical or electrical design and modeling, conductive adhesive or solder interconnect, Si-photonics, etc.

The program aims to:

1. Provide the student relevant experiences that they can put in their resume when looking for a job,
2. Foment electronics packaging as a topic to pursue in graduate school.

Find more information at IEEE/EPS/Education/Undergraduate

Interested students please contact: Dr. Somesh Kumar, DOEEE, ABV-IIITM Gwalior, M.P., India (Ph. No. +91-7009594389; Email: somesh@iiitm.ac.in)

Timeline: Aug-Dec. 2026

Qualifying requirements:

- No nationality restrictions.
- Sophomore students enrolled full-time on accredited STEM university or college which has electronics packaging graduate level research.
- B.Tech. Pursuing in the specialization of Electronics, VLSI etc.

Duration: Min. 10 weeks in single semester.

Stipend: \$750 US for 15 weeks participation

Application Deadline: 5th Aug. 2026